

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5916138

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	POWERCHIP TECHNOLOGY CORPORATION	01/15/2020
RECEIVING PARTY DATA		
Name:	POWERCHIP SEMICONDUCTOR MANUFACTURING CORPORATION	
Street Address:	NO. 18, LI-HSIN RD. 1, HSINCHU SCIENCE PARK,	
City:	HSINCHU	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Patent Number:	10020311
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	097069-US-PA	
NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	01/17/2020	
Total Attachments: 2		
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source=097069-US_ASSIGN#page2.tif		

ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

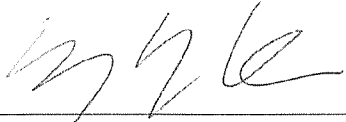
Powerchip Technology Corporation a corporation having a place of business at No. 12, Li-Hsin Rd. I, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereafter ASSIGNOR) has been assigned or otherwise has an ownership interest in certain new and useful improvements as set forth in the patents and patent applications listed in attached Appendix A.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR hereby:

- 1) Sell(s), assign(s) and transfer(s) to **Powerchip Semiconductor Manufacturing Corporation**, a corporation having a place of business at No. 18, Li-Hsin Rd. I, Hsinchu Science Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as "ASSIGNEE") the entire right, title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed therein.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application(s) or any division(s), continuation(s), substitute(s), re-examination(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application(s), as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representative(s), and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that ASSIGNOR has not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signatures of Assignor and Assignee
with the execution date of this Assignment indicated beside the signature(s).

Assignor (Conveying Party):

By: 
Typed Name: STEVE CHEN
Title: CHAIRMAN
Company: **Powerchip Technology Corporation**

Date: 2020.1.15

No. 12, Li-Hsin Rd. I, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Assignee (Receiving Party):

By: 
Typed Name: CHONG-JEN HUANG
Title: CHAIRMAN
Company: **Powerchip Semiconductor Manufacturing Corporation**

Date: 2020.1.15

No. 18, Li-Hsin Rd. I, Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

Appendix A

	Title	Patent No.	Issue Date	Attorney Docket No.
1	SEMICONDUCTOR MEMORY DEVICE PROVIDED WITH DRAM CELL INCLUDING TWO TRANSISTORS AND COMMON CAPACITOR	10020311	2018/7/10	097069-US-PA